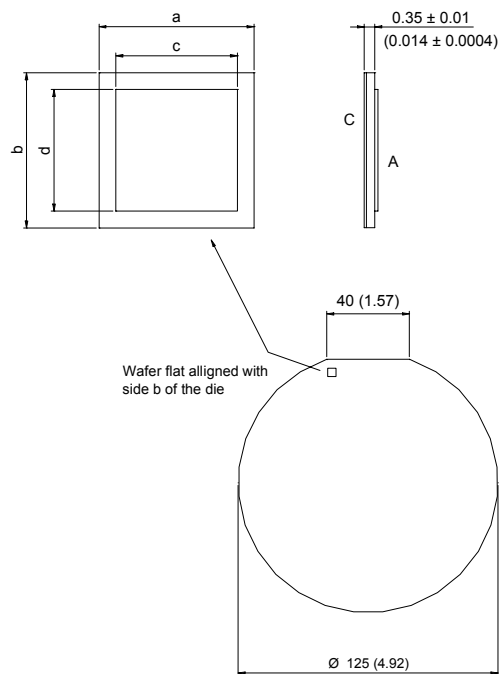


International
IOR Rectifier

FD087U02A5B

Fred Die in Wafer Form



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION (INCH):
3. DIMENSIONS AND TOLERANCES:
 $a = 2.210 \pm 0.05$
 (0.087 ± 0.002)
 $b = 2.210 \pm 0.05$
 (0.087 ± 0.002)
 $c = 1.996 \pm 0.003$
 (0.078 ± 0.0001)
 $d = 1.996 \pm 0.003$
 (0.078 ± 0.0001)
4. LETTER DESIGNATION:
A = Anode (Top Metal)
C = Cathode (Back Metal)
5. SAWING:
Recommended Blade
SEMITEC S1025 QS00 Blade
6. MINIMUM ORDER QUANTITY:
1300 die

NOT TO SCALE

Reference IR Packaged Part: MUR820 Series

Electrical Characteristics (Wafer Form)

Parameters	Units	Test Conditions
V_{FM} Maximum Forward Voltage	0.975 V	$T_J = 25^\circ\text{C}$, $I_F = 8\text{ A}$
V_{RRM} Minimum Reverse Breakdown Voltage	200 V	$T_J = 25^\circ\text{C}$, $I_{RRM} = 100\text{ }\mu\text{A}$
I_{RM} Max. Reverse Leakage Current	5 μA	$T_J = 25^\circ\text{C}$, $V_{RRM} = 200\text{ V}$
t_{rr} Typ. Reverse Recovery Time	35 ns	$I_F = 1\text{ A}$, $di_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$

Mechanical Data

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 2 KA - 3 KA)
Nominal Front Metal Composition, Thickness	99% Al, 1% Si (3 microns)
Chip Dimensions	0.087" x 0.087" (see drawing)
Reject Ink Dot Size	0.25 mm diameter minimum
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

Ordering Information Table

Device Code						
	FD	087	U	02	A	5
	1	2	3	4	5	6
1 - Fred Die						
2 - Chip Dimension in Mils:		087 = 087x087 square				
3 - Process		U = UltraFast				
4 - Voltage code Vrrm (*100) eg:		02 = 200V				
5 - Chip surface metallization:		A = Aluminium (anode), Silver (cathode)				
6 - Wafer diameter in inches						
7 - Packaging:		B = Inked Probed Unsawn Wafer (Wafer in box)				